



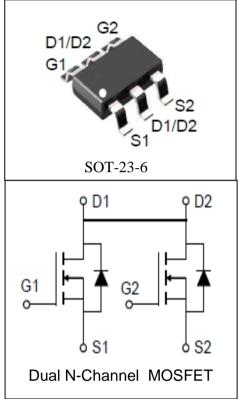
Features

- 20V/6A, $R_{DS\ (ON)} = 22m\Omega\ (Typ.)$ @ $V_{GS} = 4.5V$ $R_{DS\ (ON)} = 30m\Omega\ (Typ.)$ @ $V_{GS} = 2.5V$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free and Green Available

Applications

• Power Management

Pin Description



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit						
Common Ratings (T _A =25°C Unless Otherwise Noted)									
V_{DSS}	Drain-Source Voltage	20	\/						
V_{GSS}	Gate-Source Voltage	±12	V						
T _J	Maximum Junction Temperature	150	°C						
T _{STG}	Storage Temperature Range	-55 to 150	°C						
Is	Diode Continuous Forward Current	T _A =25°C	1.7	Α					
Mounted on Large Heat Sink									
I _{DP}	300µs Pulse Drain Current Tested	T _A =25°C	24	Α					
I _D	Continuous Drain Current(VGS=4.5V)	T _A =25°C	6	Α					
טי		T _A =70°C	4.5	Α					
В	Marsina de Barra Biantina	T _A =25°C	1.25	۱۸/					
P_D	Maximum Power Dissipation	T _A =70°C	0.8	W					
R _{eJA}	Thermal Resistance-Junction to Ambier	100	°C/W						



Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

Cumbal	Parameter	Toot Condition	RU8205C6			l lmi4	
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit	
Static Cha	aracteristics	•					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20			V	
	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V			1	^	
I _{DSS}		T _J =85°C	,		30	μΑ	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250\mu A$	0.5	0.7	1.5	V	
I _{GSS}	Gate Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$			±100	nA	
3		V _{GS} =4.5V, I _{DS} =6A		22	30	mΩ	
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =2.5V, I _{DS} =5A		30	40	mΩ	
Diode Cha	aracteristics						
V _{SD}	Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V			1	V	
Dynamic	Characteristics (4)						
R_G	Gate Resistance	V_{GS} =0V, V_{DS} =0V, F =1MHz		1.8		Ω	
C _{iss}	Input Capacitance	Vgs=0V,		580		pF	
C _{oss}	Output Capacitance	V _{DS} =10V,		120			
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz		95			
t _{d(ON)}	Turn-on Delay Time			5		- ns	
t _r	Turn-on Rise Time	Vdd=10V, Rl=1.7Ω, Ids=6A, Vgen=4.5V,		11			
t _{d(OFF)}	Turn-off Delay Time	RG= 6Ω , VGEN=4.5V,		38			
t _f	Turn-off Fall Time			13			
Gate Cha	rge Characteristics						
Q _g	Total Gate Charge			10	14		
Q _{gs}	Gate-Source Charge	Vps=16V, Vgs=4.5V, Ips=6A		1.5		nC	
Q_{gd}	Gate-Drain Charge	100-071		3.4			

Notes: ①Pulse width limited by safe operating area.

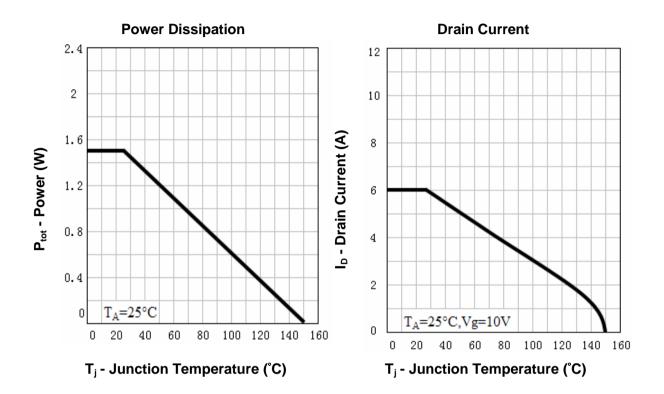
②When mounted on 1 inch square copper board, t ≤10sec.

③Pulse test ; Pulse width≤300μs, duty cycle≤2%.

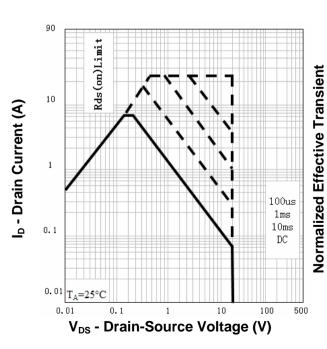
④Guaranteed by design, not subject to production testing.



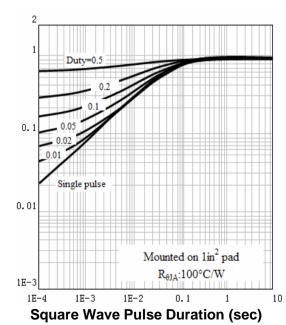
Typical Characteristics



Safe Operation Area



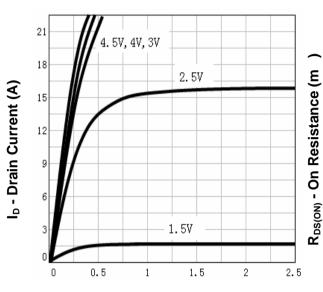
Thermal Transient Impedance





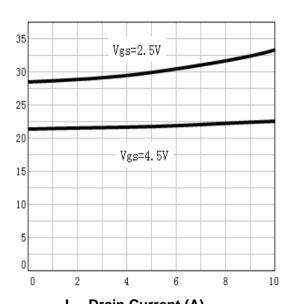
Typical Characteristics

Output Characteristics



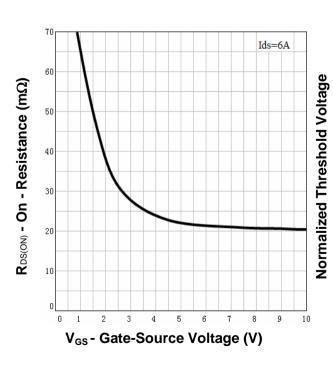
V_{DS} - Drain-Source Voltage (V)

Drain-Source On Resistance

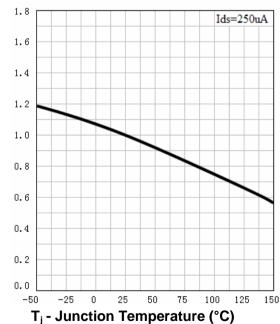


I_D - Drain Current (A)

Drain-Source On Resistance



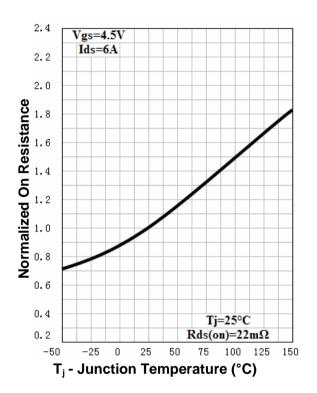
Gate Threshold Voltage



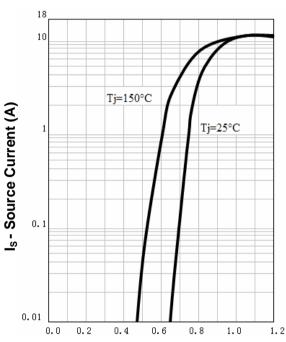


Typical Characteristics

Drain-Source On Resistance

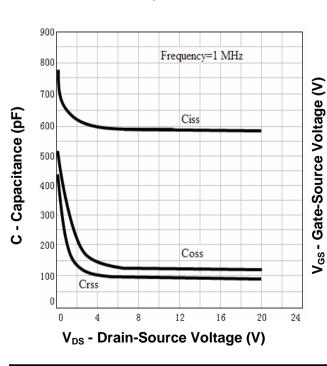


Source-Drain Diode Forward

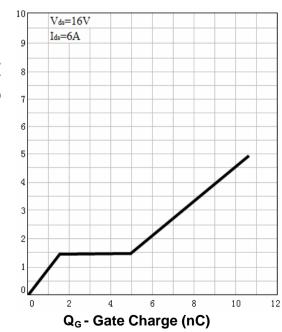


V_{SD} - Source-Drain Voltage (V)

Capacitance

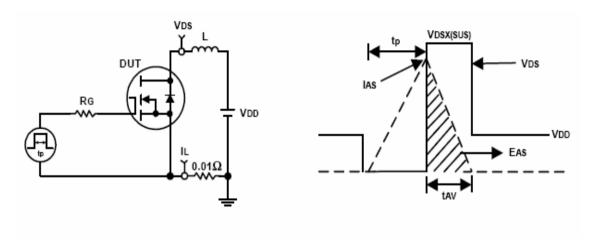


Gate Charge

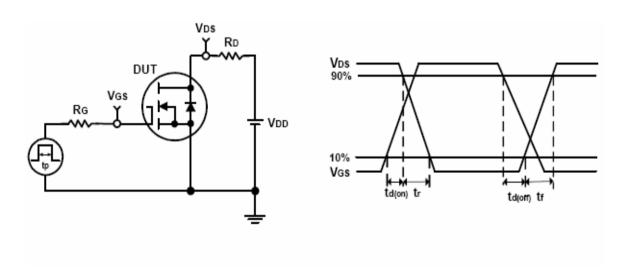




Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms





Ordering and Marking Information

Device	Marking ¹	Package	Packaging	Quantity	Reel Size	Tape width
RU8205C6	4XYWW	SOT-23-6	Tape&Reel	3000	7''	8mm

① The following characters could be different and means:

X =Assembly site code

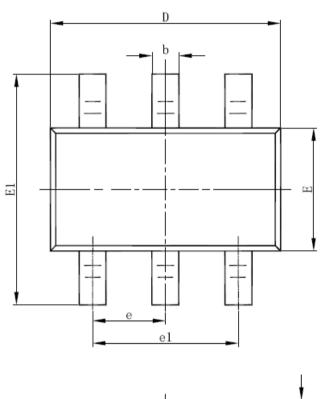
Y =Year

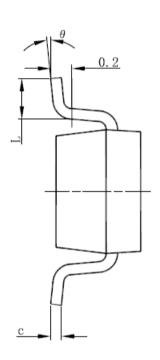
WW =Work Week

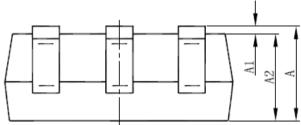


Package Information

SOT-23-6







SYMBOL	MM		INCH		GVA (DO)	MM		INCH	
STWIDOL	MIN	MAX	MIN	MAX	SYMBOL	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049	Е	1.500	1.700	0.059	0.067
A1	0.000	0.100	0.000	0.004	E1	2.650	2.950	0.104	0.116
A2	1.050	1.150	0.041	0.045	e	0.950(BSC)		0.037(BSC)	
b	0.300	0.500	0.012	0.020	e1	1.800	2.000	0.071	0.079
c	0.100	0.200	0.004	0.008	L	0.300	0.600	0.012	0.024
D	2.820	3.020	0.111	0.119	θ	0°	8°	0°	8°

ALL DIMENSIONS REFER TO JEDEC STANDARD DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS



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